



SBAS233 - DECEMBER 2001

# 16-Bit, Dual Voltage Output DIGITAL-TO-ANALOG CONVERTER

### **FEATURES**

- LOW POWER: 4mW
- UNIPOLAR OR BIPOLAR OPERATION
- SETTLING TIME: 10µs to 0.003% FSR
- 15-BIT LINEARITY AND MONOTONICITY: -40°C to +85°C
- RESET TO MID-SCALE (DAC7642) OR ZERO-SCALE (DAC7643)
- DATA READBACK
- DOUBLE-BUFFERED DATA INPUTS

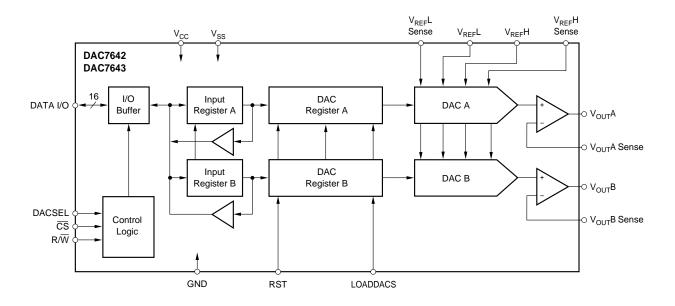
### **APPLICATIONS**

- PROCESS CONTROL
- CLOSED-LOOP SERVO-CONTROL
- MOTOR CONTROL
- DATA ACQUISITION SYSTEMS
- DAC-PER-PIN PROGRAMMERS

### DESCRIPTION

The DAC7642 and DAC7643 are dual channel, 16-bit, voltage output Digital-to-Analog Converters (DACs) which provide 15-bit monotonic performance over the specified temperature range. They accept 16-bit parallel input data, have double-buffered DAC input logic (allowing simultaneous update of all DACs), and provide a readback mode of the internal input registers. Programmable asynchronous reset clears all registers to a mid-scale code of 8000<sub>H</sub> (DAC7642) or to a zero-scale code of 0000<sub>H</sub> (DAC7643). These DACs can operate from a single +5V supply or from +5V and -5V supplies, providing an output range of 0 to +2.5V or -2.5V to +2.5V, respectively.

Low power and small size per DAC make the DAC7642 and DAC7643 ideal for automatic test equipment, DAC-per-pin programmers, data acquisition systems, and closed-loop servo-control. The DAC7642 and DAC7643 are available in a LQFP-32 package and specified over a -40°C to +85°C temperature range.





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### **ABSOLUTE MAXIMUM RATINGS(1)**

V <sub>CC</sub> to V <sub>SS</sub>	0.3V to 11V
V <sub>CC</sub> to GND	0.3V to 5.5V
V <sub>REF</sub> L to V <sub>SS</sub>	0.3V to (V <sub>CC</sub> - V <sub>SS</sub> )
V <sub>CC</sub> to V <sub>REF</sub> H	0.3V to (V <sub>CC</sub> - V <sub>SS</sub> )
V <sub>REF</sub> H to V <sub>REF</sub> L	0.3V to (V <sub>CC</sub> - V <sub>SS</sub> )
Digital Input Voltage to GND	0.3V to V <sub>CC</sub> + 0.3V
Digital Output Voltage to GND	0.3V to V <sub>CC</sub> + 0.3V
Maximum Junction Temperature	+150°C
Operating Temperature Range	40°C to +85°C
Storage Temperature Range	65°C to +125°C
Lead Temperature (soldering, 10s)	+300°C

NOTE: (1) Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

# ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### PACKAGE/ORDERING INFORMATION

PRODUCT	MONOTONICITY	PACKAGE-LEAD	PACKAGE DESIGNATOR <sup>(1)</sup>	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
DAC7642VF	14 Bits	LQFP-32	VF "	–40°C to +85°C "	DAC7642	DAC7642VFT DAC7642VFR	Tape and Reel, 250 Tape and Reel, 1000
DAC7642VFB	15 Bits	LQFP-32 "	VF "	–40°C to +85°C "	DAC7642B "	DAC7642VFBT DAC7642VFBR	Tape and Reel, 250 Tape and Reel, 1000
DAC7643VF	14 Bits	LQFP-32 "	VF "	–40°C to +85°C "	DAC7643	DAC7643VFT DAC7643VFR	Tape and Reel, 250 Tape and Reel, 1000
DAC7643VFB	15 Bits "	LQFP-32 "	VF "	–40°C to +85°C "	DAC7643B "	DAC7643VFBT DAC7643VFBR	Tape and Reel, 250 Tape and Reel, 1000

NOTE: (1) For the most current specifications and package information, refer to our web site at www.ti.com.



# **ELECTRICAL CHARACTERISTICS (Dual Supply)**

At  $T_A = T_{MIN}$  to  $T_{MAX}$ ,  $V_{CC} = +5V$ ,  $V_{SS} = -5V$ ,  $V_{REF}H = +2.5V$ , and  $V_{REF}L = -2.5V$ , unless otherwise noted.

			DAC7642VI DAC7643VI			AC7642VF AC7643VF		
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
ACCURACY Linearity Error Linearity Match Differential Linearity Error Monotonicity, T <sub>MIN</sub> to T <sub>MAX</sub> Bipolar Zero Error Bipolar Zero Error Drift Full-Scale Error Full-Scale Error Drift Bipolar Zero Matching Full-Scale Mat	Channel-to-Channel Matching Channel-to-Channel Matching At Full-Scale	14	±3 ±4 ±2 ±1 5 ±1 5 ±1 ±1 10	±4 ±3 ±3 10 ±3 10 ±3 ±3 100	15	±2 ±2 ±1 * * * * ±1 ±1 *	±3 ±2 * * * * * ±3 ±3 *	LSB LSB Bits mV ppm/°C mV ppm/°C mV mV ppm/V
ANALOG OUTPUT Voltage Output Output Current Maximum Load Capacitance Short-Circuit Current Short-Circuit Duration	$R_L = 10k\Omega$ No Oscillation GND, $V_{CC}$ or $V_{SS}$	V <sub>REF</sub> L −1.25	500 -10, +30 Indefinite	V <sub>REF</sub> H +1.25	*	* * *	*	V mA pF mA
REFERENCE INPUT Ref High Input Voltage Range Ref Low Input Voltage Range Ref High Input Current Ref Low Input Current	33 33	V <sub>REF</sub> L + 1.25 -2.5	500 -500	+2.5 V <sub>REF</sub> H – 1.25	*	* *	*	V V μΑ μΑ
DYNAMIC PERFORMANCE Settling Time Channel-to-Channel Crosstalk Digital Feedthrough Output Noise Voltage DAC Glitch	To ±0.003%, 5V Output Step See Figure 5 f = 10kHz 7FFF <sub>H</sub> to 8000 <sub>H</sub> or 8000 <sub>H</sub> to 7FFF <sub>H</sub>		8 0.5 2 60 40	10		* * * *	*	μs LSB nV-s nV/√Hz nV-s
DIGITAL INPUT  V <sub>IH</sub> V <sub>IL</sub> I <sub>IH</sub> I <sub>IL</sub>		0.7 • V <sub>CC</sub>		0.3 • V <sub>CC</sub> ±10 ±10	*		* * *	V V μΑ μΑ
<b>DIGITAL OUTPUT</b> V <sub>OH</sub> V <sub>OL</sub>	I <sub>OH</sub> = -0.8mA I <sub>OL</sub> = 1.2mA	3.6	4.5 0.3	0.4	*	* *	*	<b>&gt; &gt;</b>
POWER SUPPLY VCC VSS ICC ISS Power		+4.75 -5.25 -1.2	+5.0 -5.0 0.7 -0.8 7.5	+5.25 -4.75 1.1	* *	* * * *	* * *	V V mA mA mW
TEMPERATURE RANGE Specified Performance		-40		+85	*		*	°C

 $<sup>\</sup>ensuremath{\texttt{*}}$  Specifications same as DAC7642VF and DAC7643VF.

# **ELECTRICAL CHARACTERISTICS (Single Supply)**

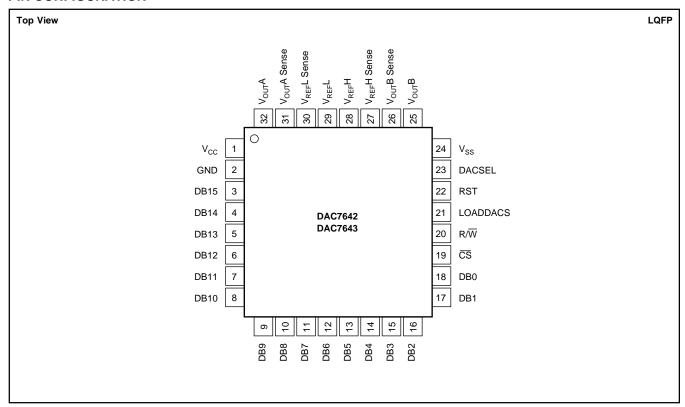
At  $T_A = T_{MIN}$  to  $T_{MAX}$ ,  $V_{CC} = +5V$ ,  $V_{SS} = 0V$ ,  $V_{REF}H = +2.5V$ , and  $V_{REF}L = 0V$ , unless otherwise noted.

			DAC7642VI DAC7643VI			AC7642VF AC7643VF		
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
ACCURACY Linearity Error <sup>(1)</sup> Linearity Match Differential Linearity Error			±3 ±4 ±2	±4 ±3		±2 ±2 ±1	±3 ±2	LSB LSB LSB
Monotonicity, T <sub>MIN</sub> to T <sub>MAX</sub> Zero-Scale Error Zero-Scale Error Drift Full-Scale Error		14	±1 5 ±1	±3 10 ±3	15	* *	* *	Bits mV ppm/°C mV
Full-Scale Error Drift Zero-Scale Matching Full-Scale Matching Power-Supply Rejection Ratio (PSRR)	Channel-to-Channel Matching Channel-to-Channel Matching At Full-Scale		5 ±1 ±1 10	±3 ±3 ±3		* ±1 ±1 *	* ±3 ±3 *	ppm/°C mV mV ppm/V
ANALOG OUTPUT Voltage Output Output Current Maximum Load Capacitance Short-Circuit Current Short-Circuit Duration	$R_L = 10k\Omega$ No Oscillation  GND or $V_{CC}$	0 -1.25	500 -10, +30 Indefinite	V <sub>REF</sub> H +1.25	*	* *	*	V mA pF mA
REFERENCE INPUT Ref High Input Voltage Range Ref Low Input Voltage Range Ref High Input Current Ref Low Input Current		V <sub>REF</sub> L + 1.25 0	250 -250	+2.5 V <sub>REF</sub> H – 1.25	*	* *	*	V V μΑ μΑ
DYNAMIC PERFORMANCE Settling Time Channel-to-Channel Crosstalk Digital Feedthrough Output Noise Voltage, f = 10kHz DAC Glitch	To ±0.003%, 2.5V Output Step See Figure 6 7FFF <sub>H</sub> to 8000 <sub>H</sub> or 8000 <sub>H</sub> to 7FFF <sub>H</sub>		8 0.5 2 60 40	10		* * * *	*	μs LSB nV-s nV/√Hz nV-s
DIGITAL INPUT  V <sub>IH</sub> V <sub>IL</sub> I <sub>IH</sub> I <sub>IL</sub>		0.7 • V <sub>CC</sub>		0.3 • V <sub>CC</sub> ±10 ±10	*		* * *	V V μΑ μΑ
DIGITAL OUTPUT V <sub>OH</sub> V <sub>OL</sub>	I <sub>OH</sub> = -0.8mA I <sub>OL</sub> = 1.2mA	3.6	4.5 0.3	0.4	*	* *	*	V V
POWER SUPPLY V <sub>CC</sub> V <sub>SS</sub> I <sub>CC</sub> Power		+4.75 0	+5.0 0 0.5 2.5	+5.25 0 0.9 4.5	*	* * * *	* * * *	V V mA mW
TEMPERATURE RANGE Specified Performance		-40		+85	*		*	°C

<sup>\*</sup> Specifications same as DAC7642VF and DAC7643VF.

NOTE: (1) If  $V_{SS} = 0V$ , specification applies at Code  $0040_H$  and above due to possible negative zero-scale error.

#### **PIN CONFIGURATION**



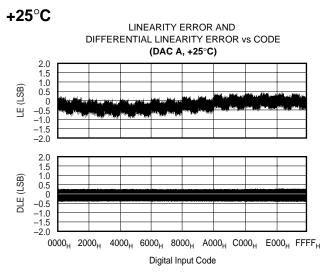
#### **PIN DESCRIPTIONS**

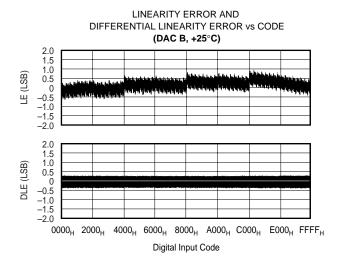
PIN	NAME	DESCRIPTION	PIN	NAME	DESCRIPTION
1	V <sub>CC</sub>	Positive Power Supply	20	R/W	Enabled by $\overline{CS}$ , Controls Data Read from and Write to the Input Registers.
2	GND	Ground	21	LOADDACS	DAC Output Registers Load Control. Rising edge
3	DB15	Data Bit 15, MSB	21	LOADDACS	triggered. Transfers Data from the Input Registers to
4	DB14	Data Bit 14			the DAC Registers, Updating the DAC Output.
5	DB13	Data Bit 13	22	RST	Reset, Rising Edge Triggered. DAC7642 resets to
6	DB12	Data Bit 12			mid-scale, DAC7643 resets to zero. (Resets Both
7	DB11	Data Bit 11			Input Registers and DAC Registers)
8	DB10	Data Bit 10	23	DACSEL	Enabled by CS. Selects the individual DAC Input Registers. (LOW Selects Register A, HIGH Selects
9	DB9	Data Bit 9			Register B)
10	DB8	Data Bit 8	24	$V_{SS}$	Negative Power Supply
11	DB7	Data Bit 7	25	$V_{OUT}B$	DAC B Voltage Output
12	DB6	Data Bit 6	26	V <sub>OUT</sub> B Sense	DAC B Output Amplifier Inverting Input. Used to
13	DB5	Data Bit 5			close the feedback loop at the load.
14	DB4	Data Bit 4	27	V <sub>REF</sub> H Sense	DAC A and B Reference High Sense Input
15	DB3	Data Bit 3	28	$V_{REF}H$	DAC A and B Reference High Input
16	DB2	Data Bit 2	29	$V_{OUT}L$	DAC A and B Reference Low Input
17	DB1	Data Bit 1	30	V <sub>REF</sub> L Sense	DAC A and B Reference Low Sense Input
18	DB0	Data Bit 0, LSB	31	V <sub>OUT</sub> A Sense	DAC A Output Amplifier Inverting Input. Used to
19	cs	Chip Select, Active LOW			close the feedback loop at the load.
		' '	32	V <sub>OUT</sub> A	DAC A Output Voltage

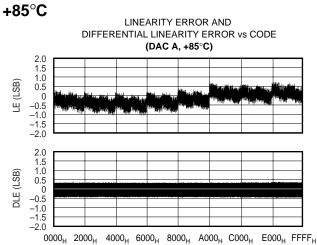


### TYPICAL CHARACTERISTICS: V<sub>SS</sub> = 0V

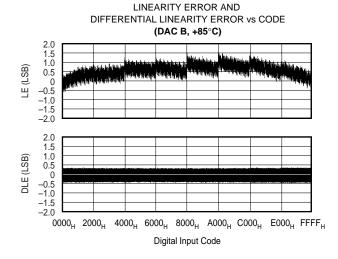
At  $T_A = +25$ °C,  $V_{CC} = +5V$ ,  $V_{SS} = 0V$ ,  $V_{REF}H = +2.5V$ ,  $V_{REF}L = 0V$ , representative unit, unless otherwise specified.

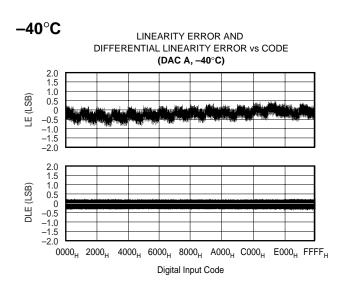


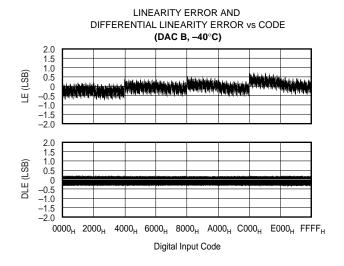




Digital Input Code

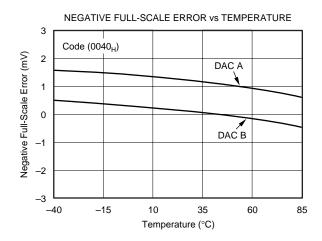


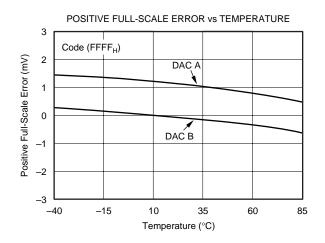


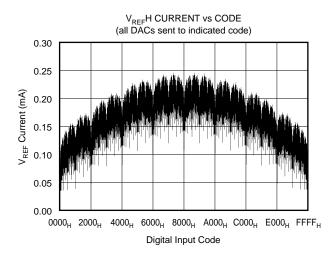


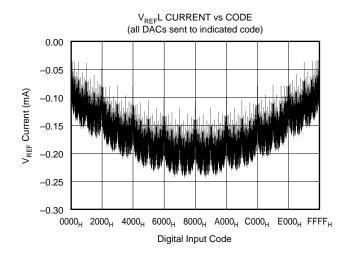
# TYPICAL CHARACTERISTICS: V<sub>SS</sub> = 0V (Cont.)

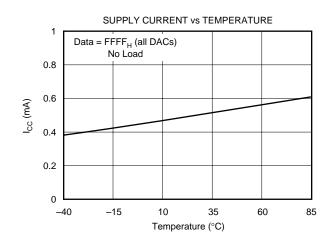
At  $T_A = +25^{\circ}C$ ,  $V_{CC} = +5V$ ,  $V_{SS} = 0V$ ,  $V_{REF}H = +2.5V$ ,  $V_{REF}L = 0V$ , representative unit, unless otherwise specified.

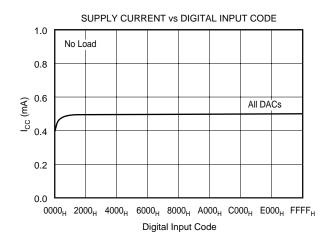






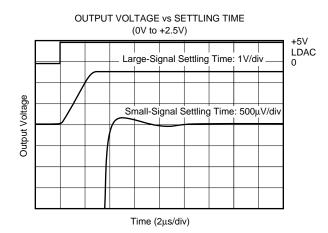


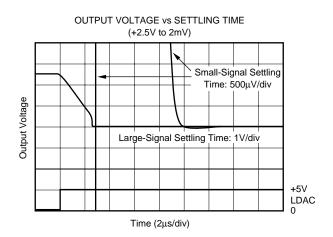


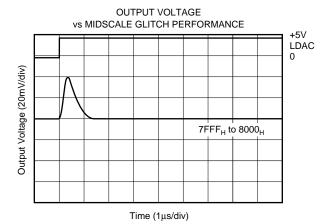


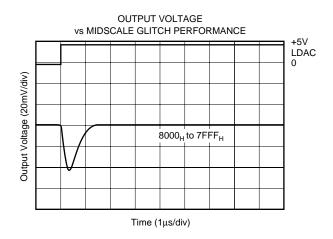
# TYPICAL CHARACTERISTICS: $V_{SS} = 0V$ (Cont.)

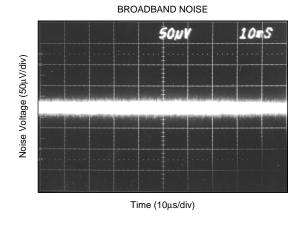
At  $T_A = +25$ °C,  $V_{CC} = +5V$ ,  $V_{SS} = 0V$ ,  $V_{REF}H = +2.5V$ ,  $V_{REF}L = 0V$ , representative unit, unless otherwise specified.

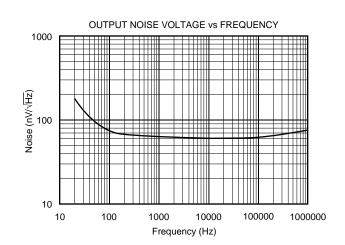






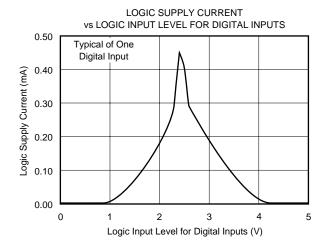


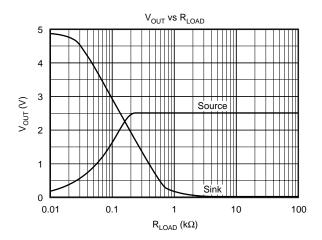




## TYPICAL CHARACTERISTICS: V<sub>SS</sub> = 0V (Cont.)

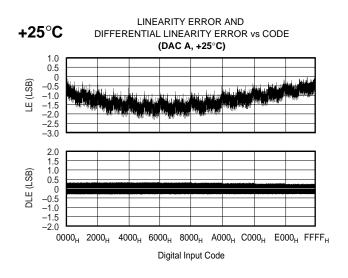
At  $T_A = +25$ °C,  $V_{CC} = +5V$ ,  $V_{SS} = 0V$ ,  $V_{REF}H = +2.5V$ ,  $V_{REF}L = 0V$ , representative unit, unless otherwise specified.

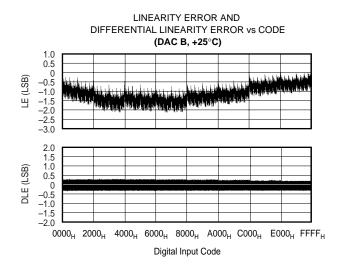


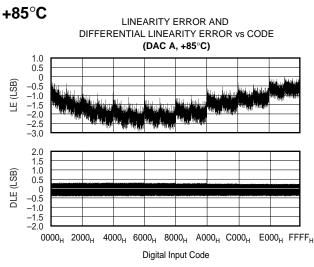


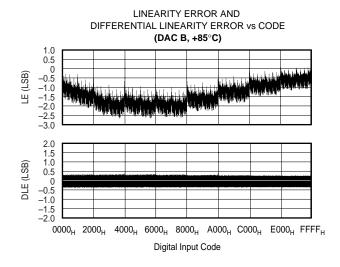
## $V_{SS} = -5V$

At  $T_A = +25^{\circ}\text{C}$ ,  $V_{CC} = +5\text{V}$ ,  $V_{SS} = -5\text{V}$ ,  $V_{REF}H = +2.5\text{V}$ ,  $V_{REF}L = -2.5\text{V}$ , representative unit, unless otherwise specified.



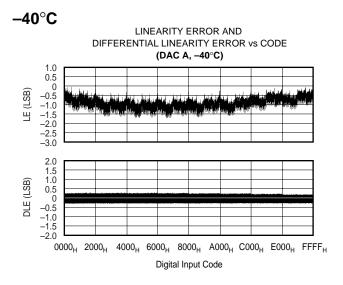


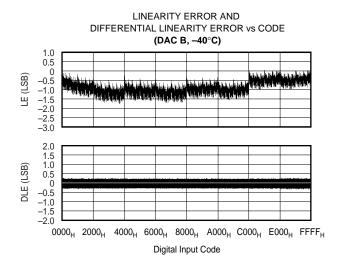


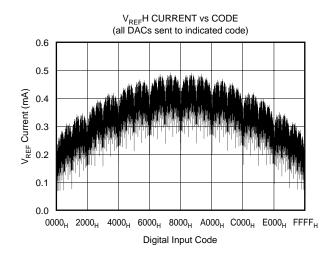


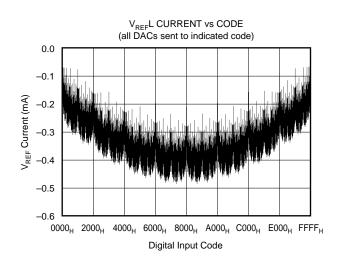
## TYPICAL CHARACTERISTICS: $V_{SS} = -5V$ (Cont.)

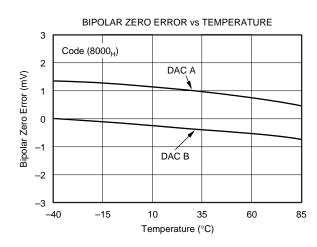
At  $T_A = +25$ °C,  $V_{CC} = +5V$ ,  $V_{SS} = -5V$ ,  $V_{REF}H = +2.5V$ ,  $V_{REF}L = -2.5V$ , representative unit, unless otherwise specified.

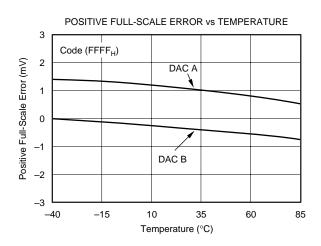








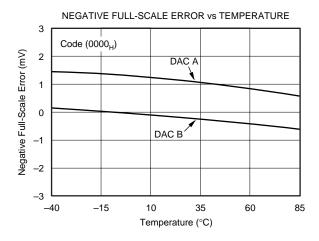


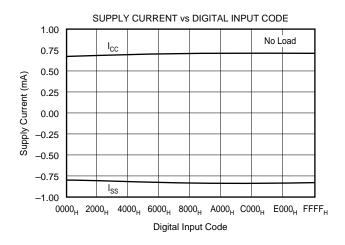


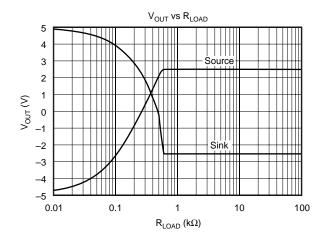


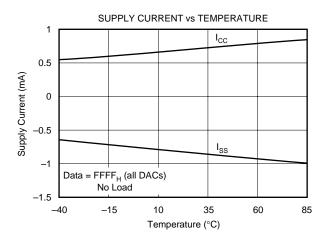
# TYPICAL CHARACTERISTICS: $V_{SS} = -5V$ (Cont.)

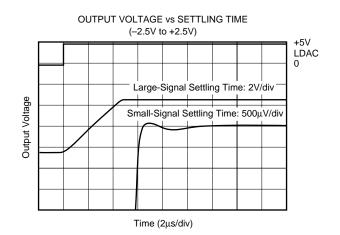
At  $T_A = +25^{\circ}\text{C}$ ,  $V_{CC} = +5\text{V}$ ,  $V_{SS} = -5\text{V}$ ,  $V_{REF}H = +2.5\text{V}$ ,  $V_{REF}L = -2.5\text{V}$ , representative unit, unless otherwise specified.

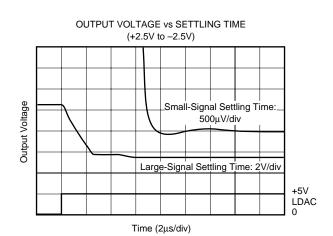






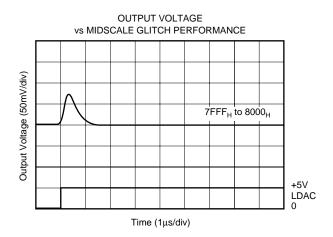


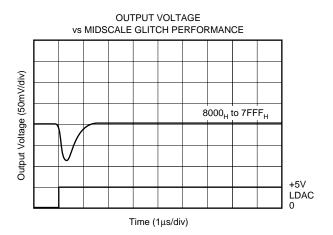




# TYPICAL CHARACTERISTICS: $V_{SS} = -5V$ (Cont.)

At  $T_A = +25^{\circ}\text{C}$ ,  $V_{CC} = +5\text{V}$ ,  $V_{SS} = -5\text{V}$ ,  $V_{REF}H = +2.5\text{V}$ ,  $V_{REF}L = -2.5\text{V}$ , representative unit, unless otherwise specified.





### THEORY OF OPERATION

The DAC7642 and DAC7643 are dual channel, voltage output, 16-bit DACs. The architecture is an R-2R ladder configuration with the three MSB's segmented followed by an operational amplifier that serves as a buffer. Each DAC has its own R-2R ladder network, segmented MSBs, and output op amp, as shown in Figure 1. The minimum voltage output (zero-scale) and maximum voltage output (full-scale) are set

by the external voltage references  $V_{REF}L$  and  $V_{REF}H$ , respectively. The digital input is a 16-bit parallel word and the DAC input registers offer a readback capability. The converters can be powered from either a single +5V supply or a dual  $\pm 5V$  supply. Each device offers a reset function which immediately sets all DAC output voltages, DAC registers and Input registers to mid-scale, code  $8000_H$  (DAC7642), or to zero-scale, code  $0000_H$  (DAC7643). See Figures 2 and 3 for the basic configurations of the DAC7642 and DAC7643.

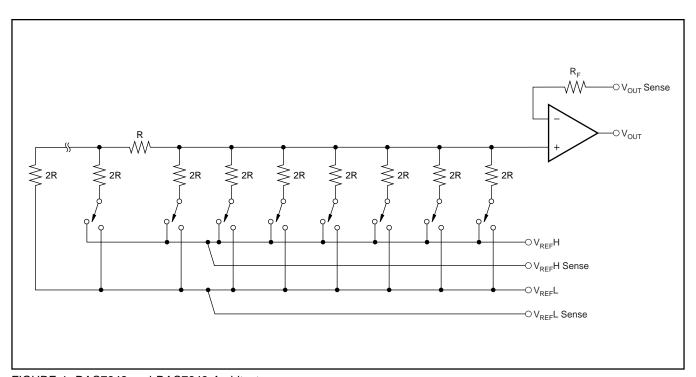


FIGURE 1. DAC7642 and DAC7643 Architecture.

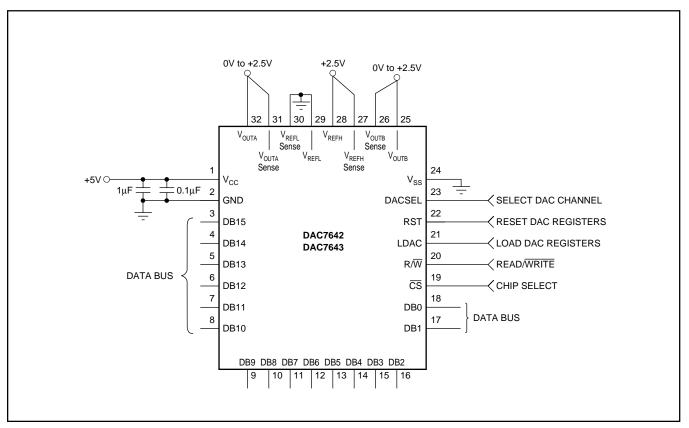


FIGURE 2. Basic Single-Supply Operation of the DAC7642 and DAC7643.

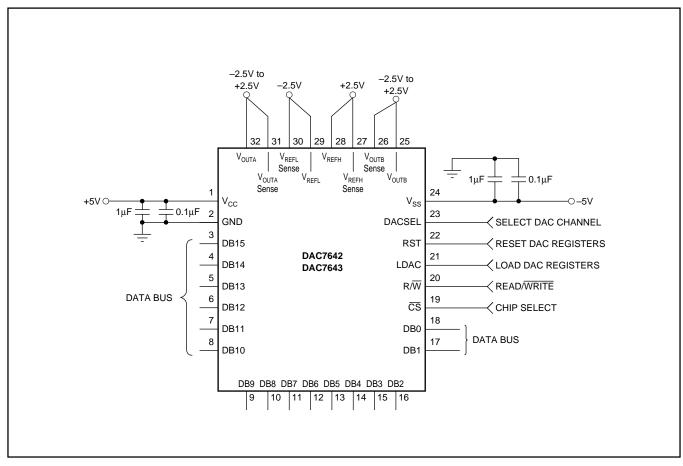


FIGURE 3. Basic Dual-Supply Operation of the DAC7642 and DAC7643.

#### **ANALOG OUTPUTS**

When  $V_{SS} = -5V$  (dual-supply operation), the output amplifier can swing to within 2.25V of the supply rails over the  $-40^{\circ}$ C to  $+85^{\circ}$ C temperature range. When  $V_{SS} = 0V$  (single-supply operation), and with  $R_{LOAD}$  also connected to ground, the output can swing to ground. Care must also be taken when measuring the zero-scale error when  $V_{SS} = 0V$ . Since the DAC output cannot swing below ground, the output voltage may not change for the first few digital input codes (0000<sub>H</sub>, 0001<sub>H</sub>, 0002<sub>H</sub>, etc.) if the output amplifier has a negative offset. At the negative limit of -2mV, the first specified output starts at code 0040<sub>H</sub>.

Due to the high accuracy of these DACs, system design problems such as grounding and contact resistance become very important. A 16-bit converter with a 2.5V full-scale range has a 1LSB value of  $38\mu V$ . With a load current of 1mA, a series wiring and connector resistance of only  $40m\Omega$  ( $R_{W2}$ ) will cause a voltage drop of  $40\mu V$ , as shown in Figure 4. To understand what this means in terms of a system layout, the resistivity of a typical 1 ounce copper-clad printed circuit board is  $1/2~m\Omega$  per square. For a 1mA load, a 10 milli-inch wide printed circuit conductor 600 milli-inches long will result in a voltage drop of  $30\mu V$ .

The DAC7642 and DAC7643 offer a force and sense output configuration for the high open-loop gain output amplifiers. This feature allows the loop around the output amplifier to be closed at the load (shown in Figure 4), thus ensuring an accurate output voltage.

#### REFERENCE INPUTS

The reference inputs,  $V_{REF}L$  and  $V_{REF}H$ , can be any voltage between  $V_{SS}+2.5V$  and  $V_{CC}-2.5V$  provided that  $V_{REF}H$  is at least 1.25V greater than  $V_{REF}L$ . The minimum output of each DAC is equal to  $V_{REF}L$  plus a small offset voltage (essentially, the offset of the output op amp). The maximum output is equal to  $V_{REF}H$  plus a similar offset voltage. Note

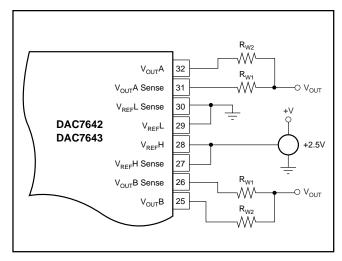


FIGURE 4. Analog Output Closed-Loop Configuration. R<sub>W</sub> represents wiring resistances.

that  $V_{SS}$  (the negative power supply) must either be connected to ground or must be in the range of -4.75 V to -5.25 V. The voltage on  $V_{SS}$  sets several bias points within the converter. If  $V_{SS}$  is not in one of these two configurations, the bias values may be in error and proper operation of the device may be affected.

The current into the  $V_{REF}H$  input and out of  $V_{REF}L$  depends on the DAC output voltages and can vary from a few microamps to approximately 0.5mA. The reference input appears as a varying load to the reference. If the references applied can sink or source the required current, a reference buffer is not required. The DAC7642 and DAC7643 feature reference drive and sense connections such that the internal errors caused by the changing reference current and the circuit impedances can be minimized. Figures 5 through 13 show different reference configurations and the effect on the linearity and differential linearity.

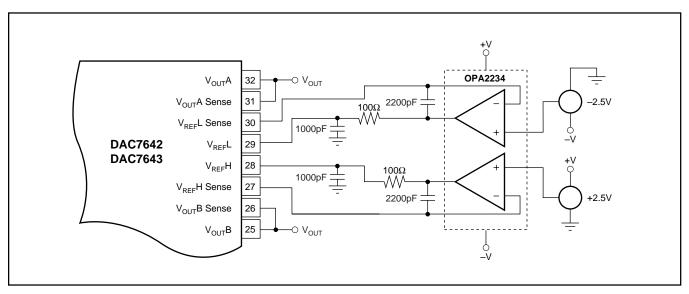


FIGURE 5. Dual Supply Configuration-Buffered References, Used for Dual-Supply Characteristic Curves.



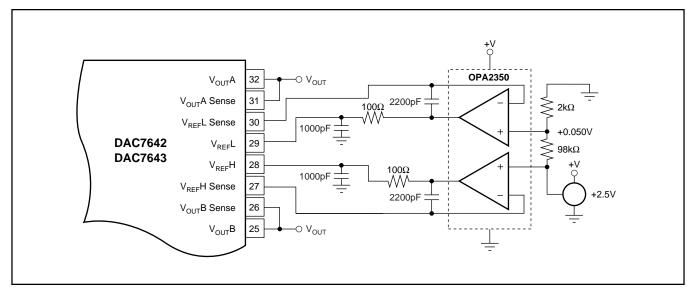


FIGURE 6. Single-Supply Buffered Reference with  $V_{REF}L$  of 50mV.

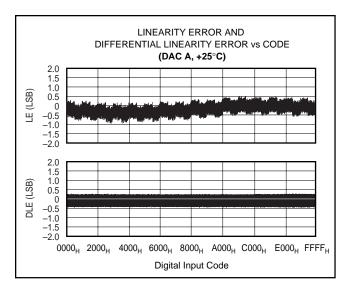


FIGURE 7. Integral Linearity and Differential Linearity Error Curves for Figure 6.

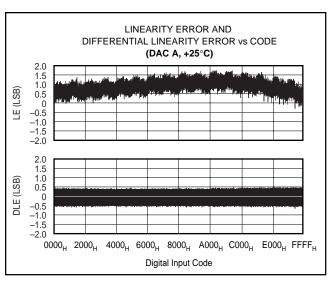


FIGURE 8. Integral Linearity and Differential Linearity Error Curves for Figure 9.

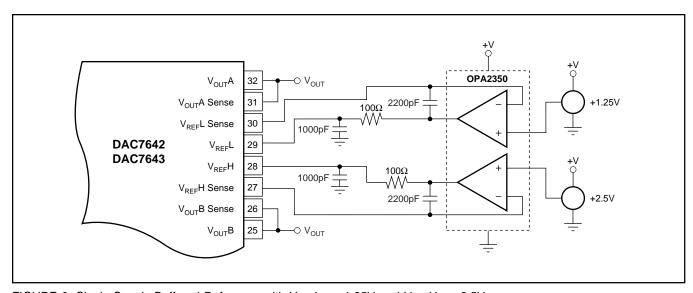


FIGURE 9. Single-Supply Buffered Reference with  $V_{REF}L$  = +1.25V and  $V_{REF}H$  = +2.5V.



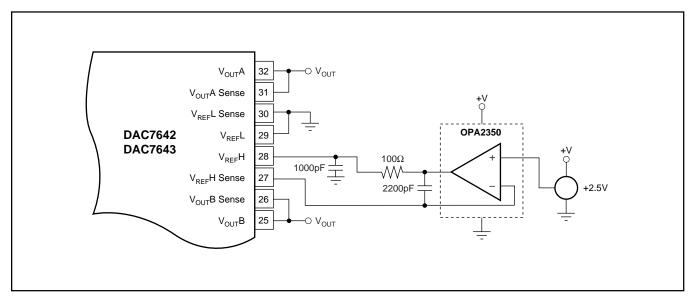


FIGURE 10. Single-Supply Buffered V<sub>REF</sub>H.

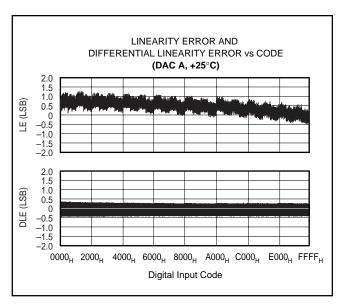


FIGURE 11. Linearity and Differential Linearity Error Curves for Figure 10.

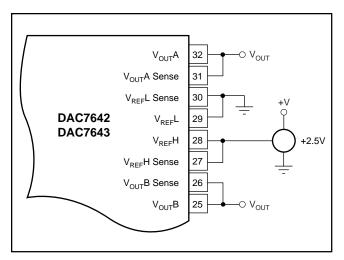


FIGURE 12. Low-Cost Single-Supply Configuration.

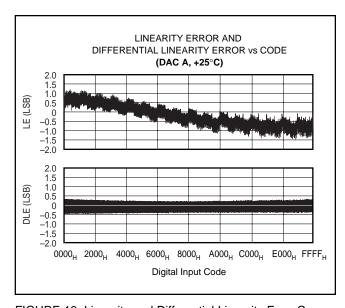


FIGURE 13. Linearity and Differential Linearity Error Curves for Figure 12.

#### **DIGITAL INTERFACE**

See Table I for the basic control logic of the DAC7642 and DAC7643. Note that each internal register is edge triggered and not level triggered. When the LOADDACS signal is transitioned from LOW to HIGH, the digital word existing in the input register is latched into the DAC register. The first set of registers (the input registers) are triggered via the DACSEL, R/W, and CS inputs. Only one of these registers can be transparent at any given time.

The double-buffered architecture is designed mainly so each DAC input register can be written to at any time without affecting the DAC outputs. All DAC voltages are updated simultaneously by the rising edge of LOADDACS. It also allows multiple devices to be updated simultaneously by sharing the LOADDACS control from the host with each device.



DACSEL	R/W	ĊS	RST	LOADDACS	INPUT REGISTER	DAC REGISTER	MODE	DAC
L	L	L	L, H	Х	Write	Hold	Write Input	Α
Н	L	L	L, H	X	Write	Hold	Write Input	В
L	Н	L	L, H	X	Read	Hold	Read Input	Α
Н	Н	L	L, H	X	Read	Hold	Read Input	В
X	X	Н	L, H	<b>↑</b>	Hold	Write	Update	All
X	X	Н	L, H	L, H	Hold	Hold	Hold	All
Х	Х	Х	<b>↑</b>	L, H	Reset	Reset	Reset	All

TABLE I. DAC7642 and DAC7643 Logic Truth Table.

#### **DIGITAL TIMING**

Figure 14 and Table II provide detailed timing for the digital interface of the DAC7642 and DAC7643.

$$V_{OUT} = V_{REF}L + \frac{\left(V_{REF}H - V_{REF}L\right) \cdot N}{65,536}$$
(1)

#### **DIGITAL INPUT CODING**

The DAC7642 and DAC7643 input data is in Straight Binary format. The output voltage is given by Equation 1:

where N is the digital input code. This equation does not include the effects of offset (zero-scale) or gain (full-scale) errors.

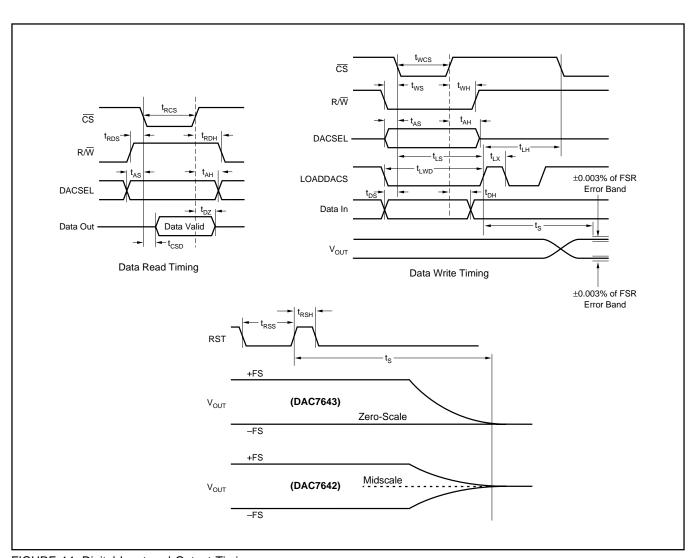


FIGURE 14. Digital Input and Output Timing.

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNITS
t <sub>RCS</sub>	CS LOW for Read	150			ns
t <sub>RDS</sub>	R/W HIGH to CS LOW	10			ns
t <sub>RDH</sub>	R/W HIGH after CS HIGH	10			ns
t <sub>DZ</sub>	CS HIGH to Data Bus in High Impedance	10		100	ns
t <sub>CSD</sub>	CS LOW to Data Bus Valid		100	150	ns
t <sub>WCS</sub>	CS LOW for Write	40			ns
t <sub>WS</sub>	R/W LOW to CS LOW	0			ns
$t_{WH}$	R/W LOW after CS HIGH	10			ns
t <sub>AS</sub>	DACSEL Valid to CS LOW	0			ns
t <sub>AH</sub>	DACSEL Valid after CS HIGH	10			ns
t <sub>LS</sub>	CS LOW to LOADDACS HIGH	30			ns
t <sub>LH</sub>	CS LOW after LOADDACS HIGH	100			ns
$t_{LX}$	LOADDACS HIGH	100			ns
t <sub>DS</sub>	Data Valid to CS LOW	0			ns
t <sub>DH</sub>	Data Valid after CS HIGH	10			ns
t <sub>LWD</sub>	LOADDACS LOW	100			ns
t <sub>RSS</sub>	RESET LOW	10			ns
t <sub>RSH</sub>	RESET HIGH	10			ns
t <sub>S</sub>	Settling Time			10	μs

TABLE II. Timing Specifications ( $T_A = -40^{\circ}C$  to +85°C).

# DIGITALLY-PROGRAMMABLE CURRENT SOURCE

The DAC7642 and DAC7643 offer a unique set of features that allows a wide range of flexibility in designing applications circuits, such as programmable current sources. The DAC7642 and DAC7643 offer both a differential reference input, as well as an open-loop configuration around the output amplifier. The open-loop configuration around the output amplifier allows a transistor to be placed within the loop to implement a digitally-programmable, unidirectional current source. The availability of a differential reference also allows programmability for both the full-scale and zero-scale currents. The output current is calculated as:

$$I_{OUT} = \left( \left( \frac{V_{REF}H - V_{REF}L}{R_{SENSE}} \right) \bullet \left( \frac{N \text{ Value}}{65,536} \right) \right) + \left( V_{REF}L / R_{SENSE} \right)$$
 (2)

Figure 15 shows a DAC7642 and DAC7643 in a 4-20mA current output configuration. The output current can be determined by Equation 3:

$$I_{OUT} = \left( \left( \frac{2.5V - 0.5V}{125\Omega} \right) \bullet \left( \frac{N \text{ Value}}{65,536} \right) \right) + \left( \frac{0.5V}{125\Omega} \right)$$
 (3)

At full-scale, the output current is 16mA plus the 4mA for the zero current. At zero scale the output current is the offset current of 4mA (0.5V/125 $\Omega$ ).

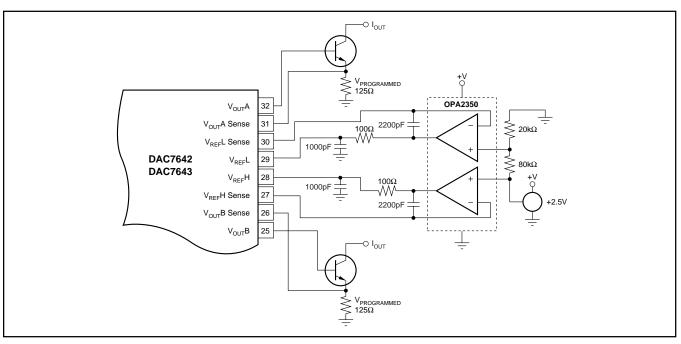
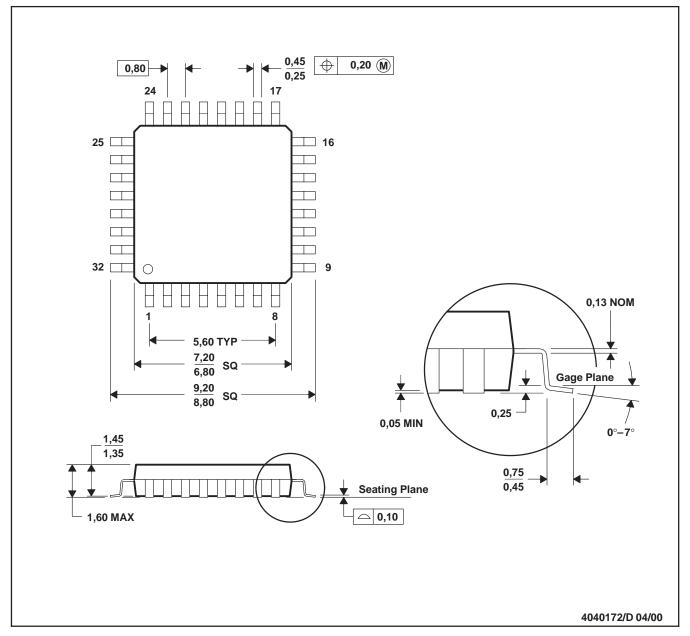


FIGURE 15. 4-20mA Digitally Controlled Current Source.



### VF (S-PQFP-G32)

#### PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.





10-Jun-2014

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
DAC7642VFBT	ACTIVE	LQFP	VF	32	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	DAC7642 B	Samples
DAC7642VFT	ACTIVE	LQFP	VF	32	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	DAC7642	Samples
DAC7642VFTG4	ACTIVE	LQFP	VF	32	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	DAC7642	Samples
DAC7643VFBR	OBSOLETE	LQFP	VF	32		TBD	Call TI	Call TI	-40 to 85	DAC7643 B	
DAC7643VFBRG4	OBSOLETE	LQFP	VF	32		TBD	Call TI	Call TI	-40 to 85		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



### **PACKAGE OPTION ADDENDUM**

10-Jun-2014

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

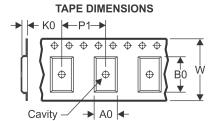
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

### **PACKAGE MATERIALS INFORMATION**

www.ti.com 26-Jan-2013

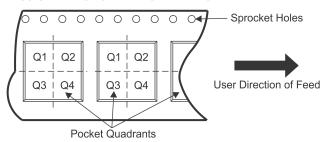
### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

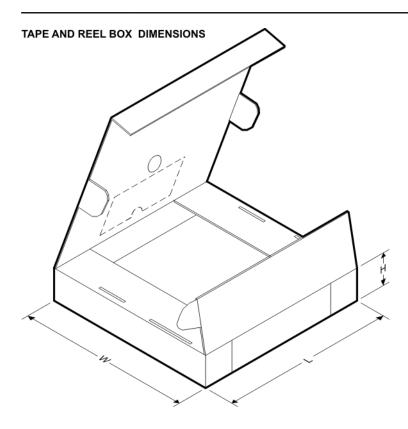
#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

I I I I (mm) IW1 (mm)I I I I I I	Device	Package Type	Package Drawing		SPQ	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	DAC7642VFBT	LQFP	VF	32	250	330.0	16.4	9.6	9.6	1.9	12.0	16.0	Q2
DAC7642VFBT LQFP VF 32 250 330.0 16.4 9.6 9.6 1.9 12.0 16.0 Q2	DAC7642VFT	LQFP	VF	32	250	330.0	16.4	9.6	9.6	1.9	12.0	16.0	Q2

www.ti.com 26-Jan-2013

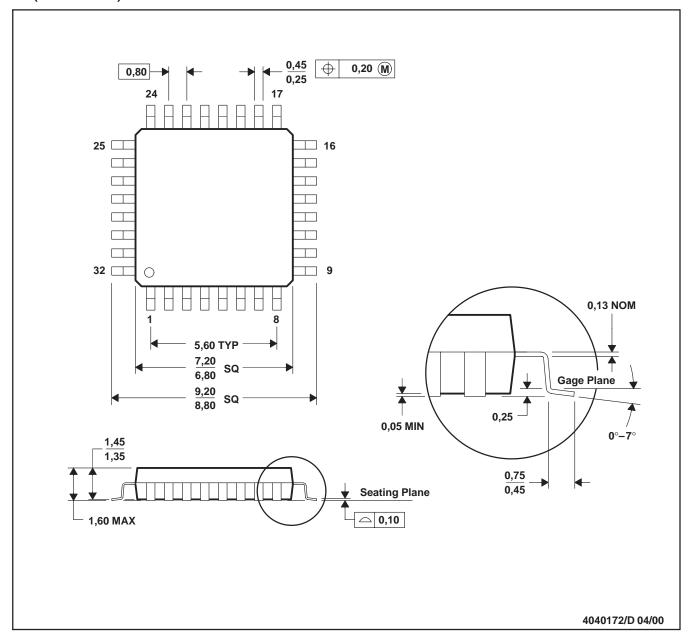


#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DAC7642VFBT	LQFP	VF	32	250	367.0	367.0	38.0
DAC7642VFT	LQFP	VF	32	250	367.0	367.0	38.0

### VF (S-PQFP-G32)

#### PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

#### IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom Amplifiers amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers <u>microcontroller.ti.com</u> Video and Imaging <u>www.ti.com/video</u>

RFID <u>www.ti-rfid.com</u>

OMAP Applications Processors <a href="https://www.ti.com/omap">www.ti.com/omap</a> TI E2E Community <a href="https://example.com/omap">e2e.ti.com/omap</a>

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>